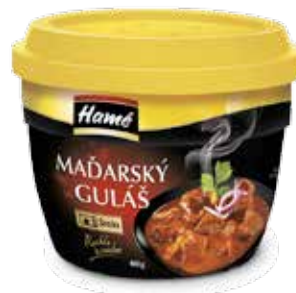


THIN WALL PACKAGING 2013

*International conference on market trends and developments in
plastics tubs, cups and tray packaging*



3-5 December 2013

Maritim Hotel, Cologne, Germany

Images courtesy of: Faech Plast AS, Micvac, Saentis Packaging AG and Silgan Plastic Food Containers

* + 19% German VAT

SPECIAL OFFER: Save €150* if you register before 1st November 2013

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THIN WALL PACKAGING 2013

3-5 December 2013, Maritim Hotel, Cologne, Germany

AMI is pleased to invite you to attend the 8th international conference on Thin Wall Packaging, which takes place from 3-5 December 2013 at the Maritim Hotel in Cologne, Germany.

The conference focus is on plastics packaging tubs, cups, trays, jars and pots. It looks at storage and functionality of plastics materials in protecting and preserving items such as meat, yoghurt, margarine, fruit and vegetables, dairy, fish, soup, and ready meals.

This year's programme looks closely at added-value packaging for long-life applications. End-use application insights and requirements are confronted with a range of barrier technologies available, as well as with material innovations. The presentations include detailed lab-tested research results, which help the industry choose fit-for-purpose solutions.

Sustainability is an on-going debate in the thin wall packaging industry, which is reflected in this year's programme. While lightweighting with packaging design is reaching its limits, the machine suppliers are innovating with solutions which enable material, energy and cost savings. Other initiatives towards material savings include foaming technologies, natural fillers and advancement in regrind technology. Furthermore, 'intelligent' packaging solutions can contribute to food waste reduction in the supply chain.

Thin Wall Packaging 2013 offers a meeting point for the industry to debate business trends and improvements in packaging technology. It provides a unique opportunity to network with the wide range of professionals involved with the plastics packaging industry at all levels of the supply chain.

EARLY BIRD REGISTRATION OFFER

Register before 1st November 2013 and pay €950* saving €150* on the full price of €1100*. There are additional discounts for group bookings. The registration fee includes attendance at all conference sessions, the Welcome Cocktail Reception, lunch and refreshment breaks on both days, and a set of conference proceedings.

SPONSOR THIS EVENT

A variety of sponsorship opportunities are available at this conference to help to promote and enhance your company's products and services to this highly targeted international audience. Contact the conference hotline for further information.

CONFERENCE VENUE

Cologne was founded over 2,000 years ago and is a good place for dining out, cultural tours and shopping. The conference will take place at the Maritim Hotel, which is on the banks of the Rhine within walking distance of the old town and ancient cathedral.

*+19% German VAT

CONFERENCE HOTLINE

Contact: Maud Lassara, Senior Conference Organiser
Tel: +44 (0) 117 924 9442
Fax: +44 (0) 117 311 1534
Email: ml@amiplastics.com

See the latest programme and confirmed speakers at:
www.amiconferences.com

C O N F E R E N C E

Tuesday 3rd December 2013

17.00 Registration
18.00-19.30 Welcome Cocktail Reception

There are no conference sessions on this day

Wednesday 4th December 2013

08.00 Registration and welcome coffee
09.00 Opening announcements

MARKET OVERVIEW

09.10 **Retortable packaging in the context of thin wall packaging**
Ms. Martyna Zimakiewicz, Packaging Consultant,
AMI CONSULTING, United Kingdom

09.40 **Single serve cup vs form/fill seal in U.S. yoghurt packaging**
Ms. Jill Goldbach, Sourcing Manager-Rigid Packaging,
GENERAL MILLS INC., United States

10.10 **Trends in ready meal packaging**
Mr. Nick Brewin, Sales and Marketing Director,
SILGAN PLASTIC FOOD CONTAINERS, United Kingdom

10.40-11.10 Morning coffee sponsored by:



11.10 **Trends in coffee packaging**
Speaker to be announced

SESSION 1 - MATERIAL ENGINEERING

11.40 **New foamed PET technology for tomorrow's food packaging revolution**
Mr. Antonio Terzoni, Marketing Manager,
COOPBOX GROUP, Italy

12.10 **PP talc compounds for food packaging**
Mr. Frans Venema, Technical Support Manager Plastics,
MONDO MINERALS BV, Netherlands

12.40-14.10 Lunch sponsored by:



14.10 **Organoleptics - explained and guaranteed**
Mr. Jacques D'heur, Injection and Coating Application Manager,
INEOS OLEFINS & POLYMERS EUROPE, Belgium

SESSION 2 - PRODUCTION OPTIMISATION

14.40 **High quality and cost efficient sheet extrusion**
Dipl.-Ing. Berthold Dröge, Technical Director,
SML, Austria

15.10-15.40 Afternoon tea

15.40 **New challenges in the production of thin wall packaging products**
Dr. Kurt Hell, Sales Manager Business Unit Packaging,
ENGEL AUSTRIA GmbH, Austria and
Mr. Philip Knapen, Application Technology Manager
Rigid Packaging,
BOREALIS, Belgium

PROGRAMME

- 16.10 **Application specific machine technology for cost effective thin wall moulding**
Dipl.-Ing. (BA) Andreas Reich, Sales Manager Packaging,
ARBURG GmbH + CO. KG, Germany
- 20.00 Conference Dinner at the Wolkenburg Restaurant

Thursday 5th December 2013

- 08.30 Registration and welcome coffee
09.00 Opening announcements

SESSION 3 - ENHANCING PRODUCT IMAGE

- 09.10 **Increasing production efficiency through innovative colour technology**
Mr. Arnaud Nombrot, Key Account Manager Packaging,
SUMITOMO DEMAG PLASTICS MACHINERY, Germany
- 09.40 **In-mold-labeling & decorating 3D IML**
Dr. Hartmut Traut, Business Director,
TREXEL GmbH, Germany
- 10.10-10.40 Morning coffee
- 10.40 **Decoration in thermoforming**
Mr. Claus Weinert, Area Sales Manager/Product Manager,
ILLIG MASCHINENBAU GmbH & Co. KG, Germany
- 11.10 **Intelligent packaging to reduce food waste**
Mr. Sorin Crainic, Director of Sales, Europe and The Middle East,
PPI PAPER PAK INDUSTRIES, United States

SESSION 4 - ADVANCEMENTS IN BARRIER TECHNOLOGY

- 11.40 **The benefits of multilayer structures – optimising barrier packaging**
Mr. Didier Houssier, Business Development Manager,
KURARAY, EVAL EUROPE N.V., Belgium
- 12.10-13.40 Lunch
- 13.40 **Innovative and cost-effective barrier solutions for thin wall packaging applications**
Mr. Steve Thomson, Strategic Account Manager,
MOLD-MASTERS EUROPA GmbH, Germany
- 14.10 **Impact of thermoforming on the oxygen permeability and thickness of thermoformed trays**
Dr. Ir. Mieke Buntinx, Professor,
UNIVERSITY HASSELT, Belgium
- 14.40 Afternoon tea and conference ends

Conference bag sponsored by:



Also sponsored by:



AMI reserves the right to alter the programme without notice.
The latest programme including any new speakers or changes to
schedules can be viewed on our website www.amiconferences.com

Save €150*

Register before 1st November 2013
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THIN WALL PACKAGING 2013: EXHIBITION SPACE

Make it easy for the delegates to find you at this busy event with your own table top exhibition space. Bring your own display stand, or just use the space to have literature and samples available and ensure that you make an impact. The table top exhibition will run throughout the conference in the spacious lobby next to the main meeting room.

Registration includes 1 delegate place!

Space is limited so to avoid disappointment please register for this service as soon as possible.

HOTEL ACCOMMODATION

Delegates are responsible for booking their own accommodation. AMI has negotiated a room rate of €156.71 for a single room and €196.49 for a double room (breakfast and taxes included) at the Maritim Hotel in Cologne, for a limited time only. To reserve a room please contact the hotel direct and state that you are attending "AMI's Thin Wall Packaging 2013".

Tel: +49 221 2027 849 Fax: +49 221 2027 826
Email: reservierung.kol@maritim.de



Image courtesy of: **Norner AS**

FIVE GOOD REASONS WHY YOU SHOULD ATTEND:

1. Review the latest market trends
2. Learn about sustainability issues
3. Assess the latest packaging innovations
4. Keep up with new materials and technology
5. Network with top international experts

